

**Amendment to the Specification:**

Please replace the title with the following amended title:

SEMICONDUCTOR DEVICE HAVING A CHIP-SIZE PACKAGE, ~~METHOD FOR~~  
~~MANUFACTURING THE SAME, AND METHOD FOR MOUNTING THE SAME~~

Before the first paragraph on page 1, please insert the following paragraph:

This nonprovisional application is a continuation of U.S. Application Number  
10/300,883, filed November 21, 2002 which is a divisional of U.S. Application Number  
09/663,616 filed September 18, 2002, now U.S. Patent No. 6,589,817, which is a  
divisional of 08/944,891 filed October 6, 1997 now U.S. Patent No. 6,246,114.

**Amendment to the Abstract:**

Please replace the Abstract of the Disclosure with the new attached Abstract of  
Disclosure submitted herewith on a separate sheet.